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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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## 30V N-Channel Power MOSFET

30V, 50A, 9mΩ

### FEATURES

- Fast switching
- Halogen Free
- G-S ESD Protection Diode Embedded

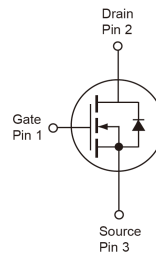
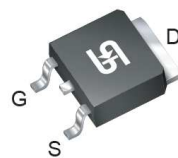
### APPLICATION

- MB / VGA / Vcore
- POL Applications
- SMPS 2<sup>nd</sup> SR

KEY PERFORMANCE PARAMETERS		
PARAMETER	VALUE	UNIT
$V_{DS}$	30	V
$R_{DS(on)}$ (max)	$V_{GS} = 10V$	9
	$V_{GS} = 4.5V$	14
$Q_g$	7.5	nC



TO-252 (DPAK)



**Notes:** Moisture sensitivity level: level 3. Per J-STD-020

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	$T_C = 25^\circ\text{C}$	50
		$T_C = 100^\circ\text{C}$	32
Pulsed Drain Current <sup>(Note 1)</sup>	$I_{DM}$	200	A
Total Power Dissipation	$P_D$	$T_C = 25^\circ\text{C}$	40
		Derate above $T_C = 25^\circ\text{C}$	0.32
Single Pulsed Avalanche Energy <sup>(Note 2)</sup>	$E_{AS}$	45	mJ
Single Pulsed Avalanche Current <sup>(Note 2)</sup>	$I_{AS}$	30	A
Operating Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	- 55 to +150	$^\circ\text{C}$

<b>THERMAL PERFORMANCE</b>			
<b>PARAMETER</b>	<b>SYMBOL</b>	<b>LIMIT</b>	<b>UNIT</b>
Junction to Case Thermal Resistance	$R_{\theta JC}$	3.1	$^{\circ}\text{C}/\text{W}$
Junction to Ambient Thermal Resistance	$R_{\theta JA}$	62	$^{\circ}\text{C}/\text{W}$

**Notes:**  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistances. The case thermal reference is defined at the solder mounting surface of the drain pins.  $R_{\theta JA}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.  $R_{\theta JA}$  shown below for single device operation on FR-4 PCB in still air.

<b>ELECTRICAL SPECIFICATIONS</b> ( $T_J = 25^{\circ}\text{C}$ unless otherwise noted)						
<b>PARAMETER</b>	<b>CONDITIONS</b>	<b>SYMBOL</b>	<b>MIN</b>	<b>TYP</b>	<b>MAX</b>	<b>UNIT</b>
<b>Static</b> (Note3)						
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	$BV_{DSS}$	30	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	$V_{GS(TH)}$	1.2	1.6	2.5	V
Gate Body Leakage	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$	$I_{GSS}$	--	--	$\pm 10$	$\mu\text{A}$
Zero Gate Voltage Drain Current	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}$	$I_{DSS}$	--	--	1	$\mu\text{A}$
	$V_{DS} = 24\text{V}, T_J = 125^{\circ}\text{C}$		--	--	10	
Forward Transconductance	$V_{DS} = 10\text{V}, I_D = 8\text{A}$	$g_{fs}$	--	9.5	--	S
Drain-Source On-State Resistance	$V_{GS} = 10\text{V}, I_D = 16\text{A}$	$R_{DS(ON)}$	--	7.5	9	m $\Omega$
	$V_{GS} = 4.5\text{V}, I_D = 8\text{A}$		--	9.6	14	
<b>Dynamic</b> (Note4)						
Total Gate Charge	$V_{DS} = 15\text{V}, I_D = 20\text{A}, V_{GS} = 4.5\text{V}$	$Q_g$	--	7.7	--	nC
Gate-Source Charge		$Q_{gs}$	--	1.9	--	
Gate-Drain Charge		$Q_{gd}$	--	2.8	--	
Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	$C_{iss}$	--	680	--	pF
Output Capacitance		$C_{oss}$	--	150	--	
Reverse Transfer Capacitance		$C_{rss}$	--	70	--	
Gate Resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	$R_g$	--	2.7	--	$\Omega$
<b>Switching</b> (Note5)						
Turn-On Delay Time	$V_{DD}=15\text{V}, V_{GS}=10\text{V}, R_G=3.3\Omega, I_D=-15\text{A}$	$t_{d(on)}$	--	4.8	--	ns
Turn-On Rise Time		$t_r$	--	12.5	--	
Turn-Off Delay Time		$t_{d(off)}$	--	27.6	--	
Turn-Off Fall Time		$t_f$	--	8.2	--	
<b>Source-Drain Diode</b> (Note3)						
Forward Voltage	$V_{GS} = 0\text{V}, I_S = 1\text{A}$	$V_{SD}$	--	--	1	V
Continuous Drain-Source Diode	$V_G=V_D=0\text{V}$	$I_S$	--	--	50	A
Pulse Drain-Source Diode	Force Current	$I_{SM}$	--	--	200	A

**Notes:**

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25\text{V}, V_{GS}=10\text{V}, L=0.1\text{mH}, I_{AS}=30\text{A}, R_G=25\Omega$ , Starting  $T_J=25^{\circ}\text{C}$ .
3. Pulse test:  $PW \leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
4. For DESIGN AID ONLY, not subject to production testing.
5. Switching time is essentially independent of operating temperature

**ORDERING INFORMATION**

<b>PART NO.</b>	<b>PACKAGE</b>	<b>PACKING</b>
TSM090N03ECP ROG	TO-252	2,500pcs / 13" Reel

**Note:**

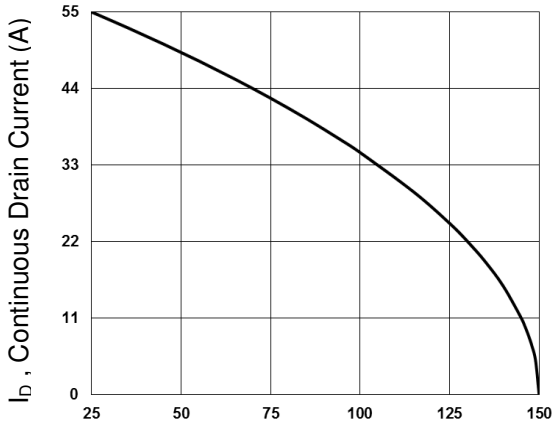
1. Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
2. Halogen-free according to IEC 61249-2-21 definition



**CHARACTERISTICS CURVES**

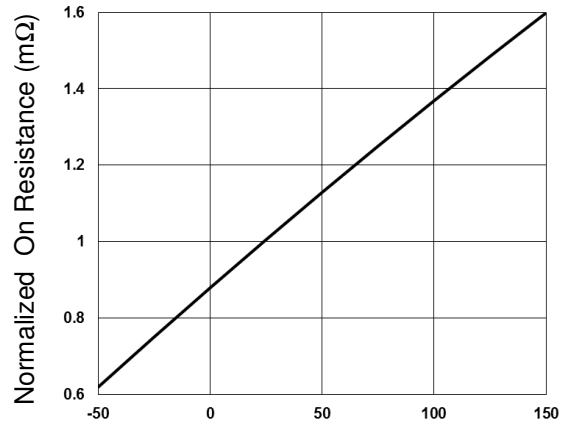
( $T_C = 25^\circ\text{C}$  unless otherwise noted)

**Continuous Drain Current vs.  $T_C$**



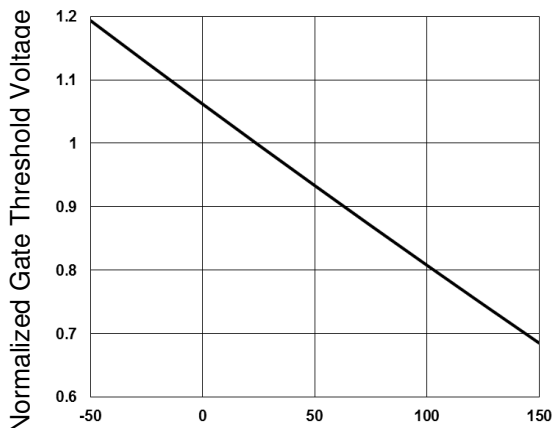
$T_C$ , Case Temperature ( $^\circ\text{C}$ )

**Normalized  $R_{DS(on)}$  vs.  $T_J$**



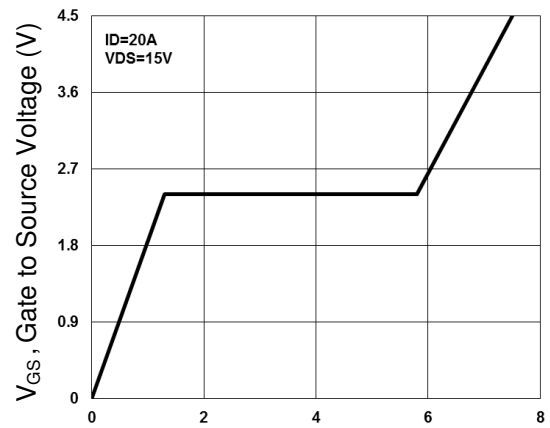
$T_J$ , Junction Temperature ( $^\circ\text{C}$ )

**Normalized  $V_{th}$  vs.  $T_J$**



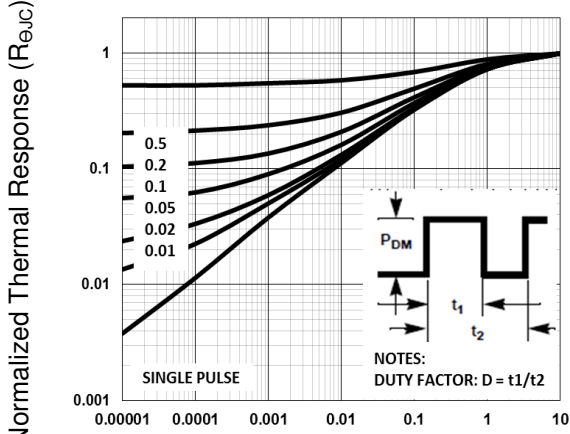
$T_J$ , Junction Temperature ( $^\circ\text{C}$ )

**Gate Charge Waveform**



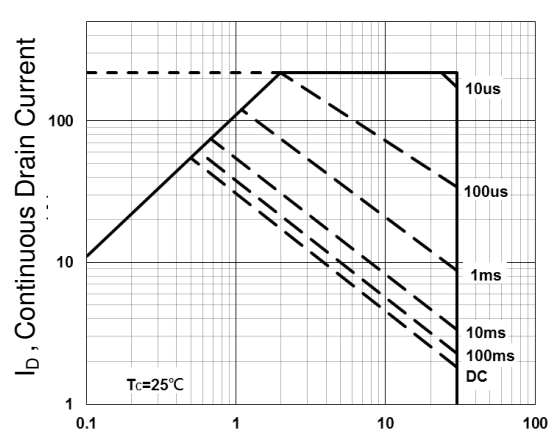
$Q_g$ , Gate Charge (nC)

**Normalized Transient Impedance**



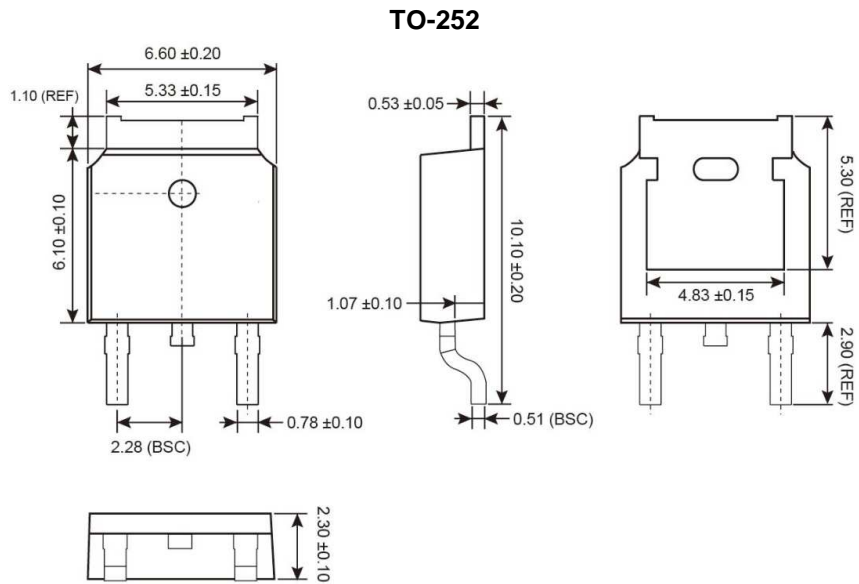
Square Wave Pulse Duration

**Maximum Safe Operation Area**

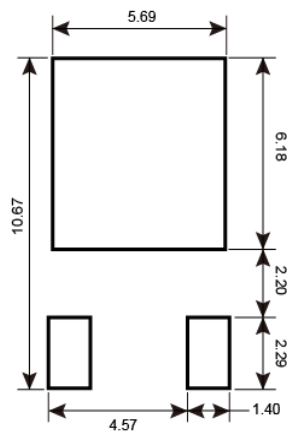


$V_{DS}$ , Drain to Source Voltage

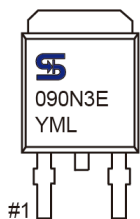
**PACKAGE OUTLINE DIMENSIONS** (Unit: Millimeters)



**SUGGESTED PAD LAYOUT** (Unit: Millimeters)



**MARKING DIAGRAM**



- Y** = Year Code
- M** = Month Code for Halogen Free Product
- O** =Jan    **P** =Feb    **Q** =Mar    **R** =Apr
- S** =May    **T** =Jun    **U** =Jul    **V** =Aug
- W** =Sep    **X** =Oct    **Y** =Nov    **Z** =Dec
- L** = Lot Code

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